



Customer-Oriented Product Engineering of Micro and Nano Devices

CORONA: Innovative Product Engineering Tools for MEMS

Christine Neuy, IVAM April 21, 2010, Forum Innovations for Industry

















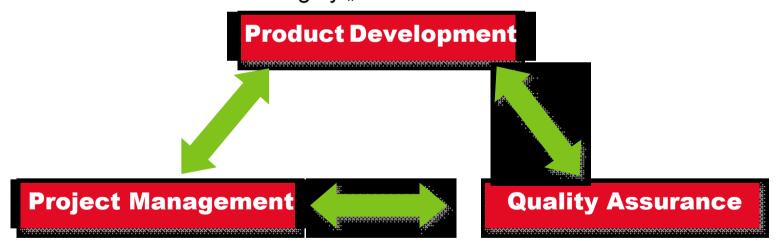


Product Engineering ...



- is the process of gradually turning the idea of a technical device into a physical realisation.
- includes both the design and the fabrication stages.

Specifying "what to do" and roughly "how to do it"



Specifying "how to do it" on a detailed level

Making sure "to do it well"

Value chain in MNT



MEMS Device Develop- ment	MEMS Design	Process (Tech- nology) Develop- ment	MEMS Wafer Manu- facturing	MEMS Assembly & Test	Marketing & Sales
Fabless Houses		MEMS Process Develop- ment Specialists		Assembly & Test Houses	Distribu- tors, Fabless Houses, Whole- salers, Trading Companies
	Design Houses, Design Centres		(Wafer) Foundry Services, Semiconductor Contract Manufacturer (SCM)		

Challenges in MNT PE



A large variety of business models

From large IDMs to specialised companies

Distributed development and manufacturing

Different companies (or departments) at different locations

SME focus

Frequently SMEs involved with small development budget

Customer orientation

Only the customer knows product and constraints

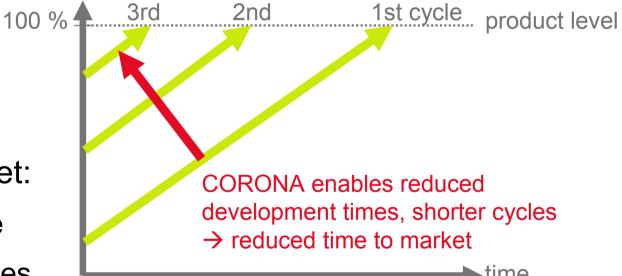
But...

There is currently no appropriate product engineering methodology and tools available to support these aspects.

Benefits from MNT PE



What can be expected from MNT product engineering?



- Shorter time-to-market:
 - Reduced cycle time
 - Fewer learning cycles
- Access to knowledge-bases on design and fabrication
 - ICT based structure and tools
 - Improved transfer of knowledge from design to production
- Customer-lead multi-site product development

Workflow in CORONA



Methodology

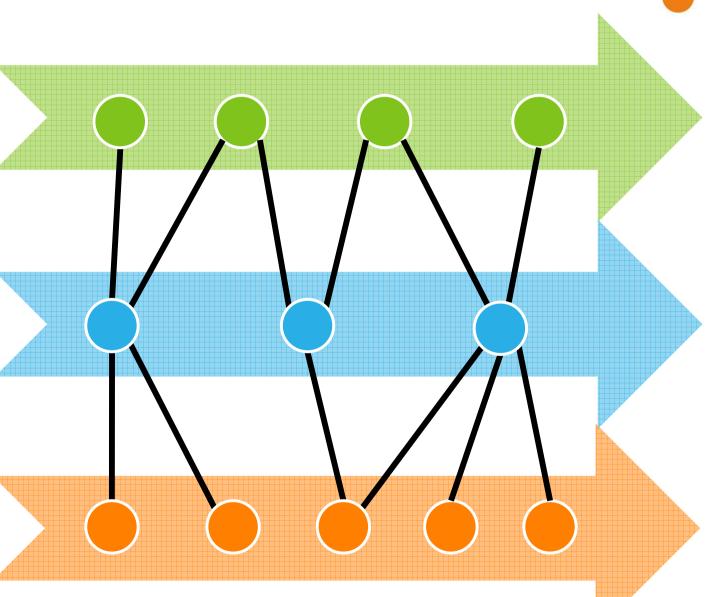
Workflow Definition

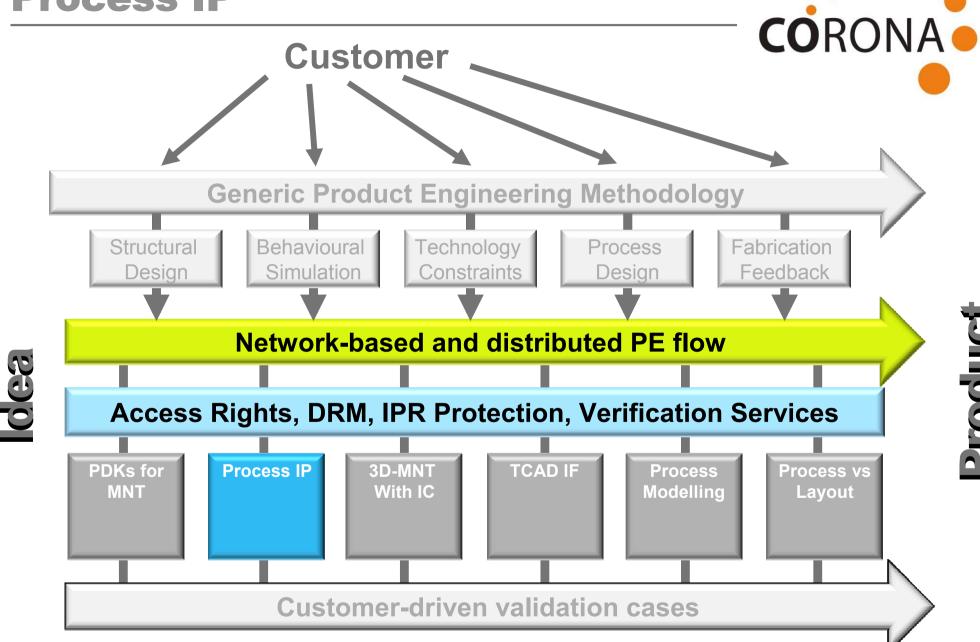
Middle Ware & Tools

Workflow/Designflow Integration

Validation

by real-life business cases





Process development cycle

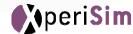












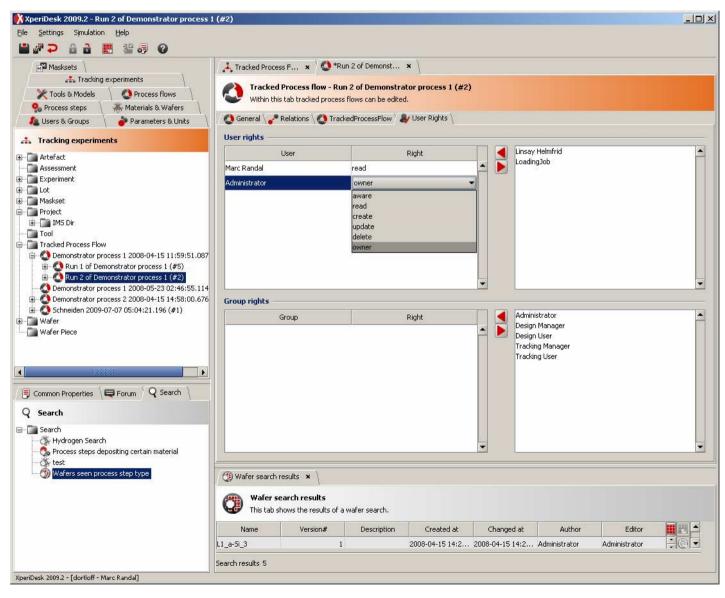




Management of Entity Rights



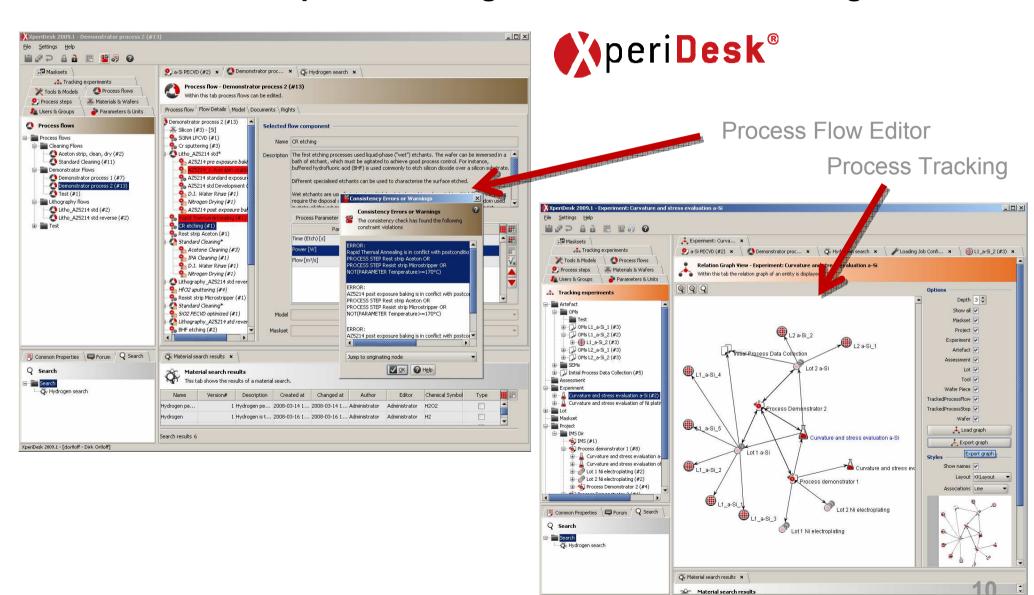




Process Tools



A framework for process design verification and tracking



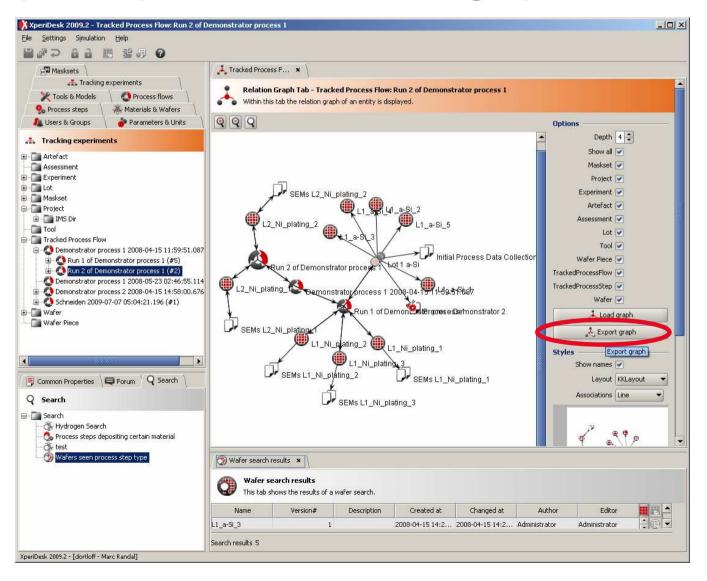
XperiDesk 2009.1 - [dortloff - Dirk Ortloff]

Ways to build PKDKs





Export experiment data from graphic view

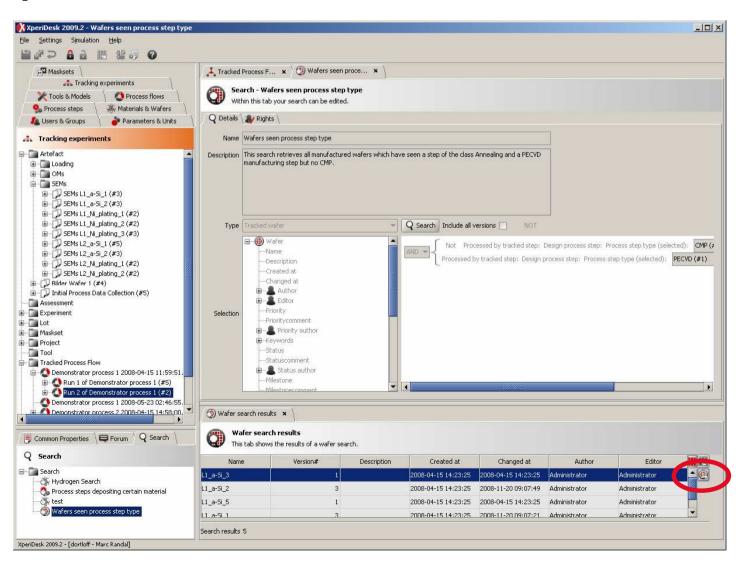


Ways to build PKDKs

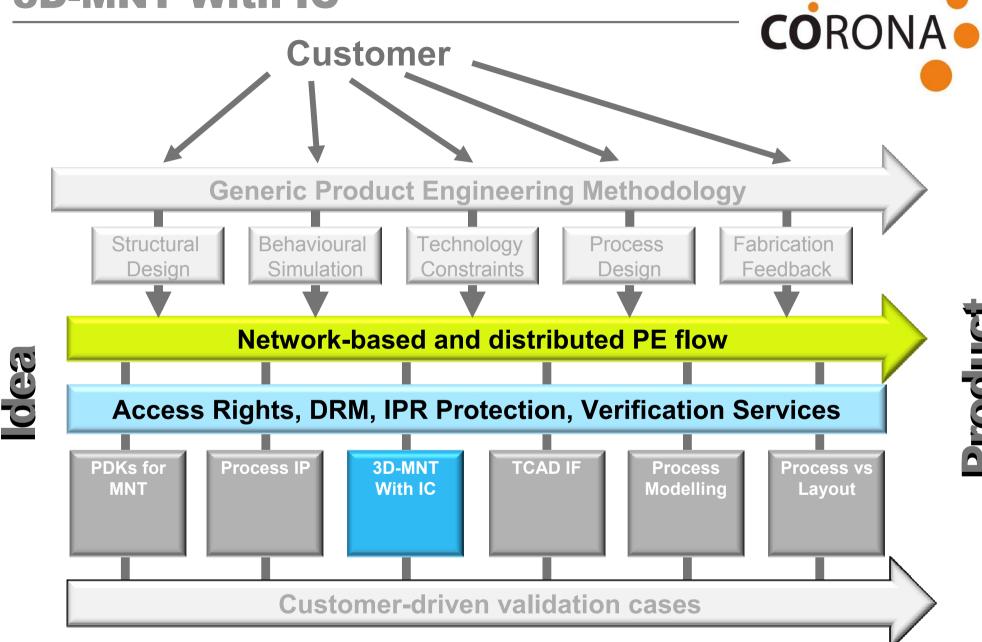




Export search results

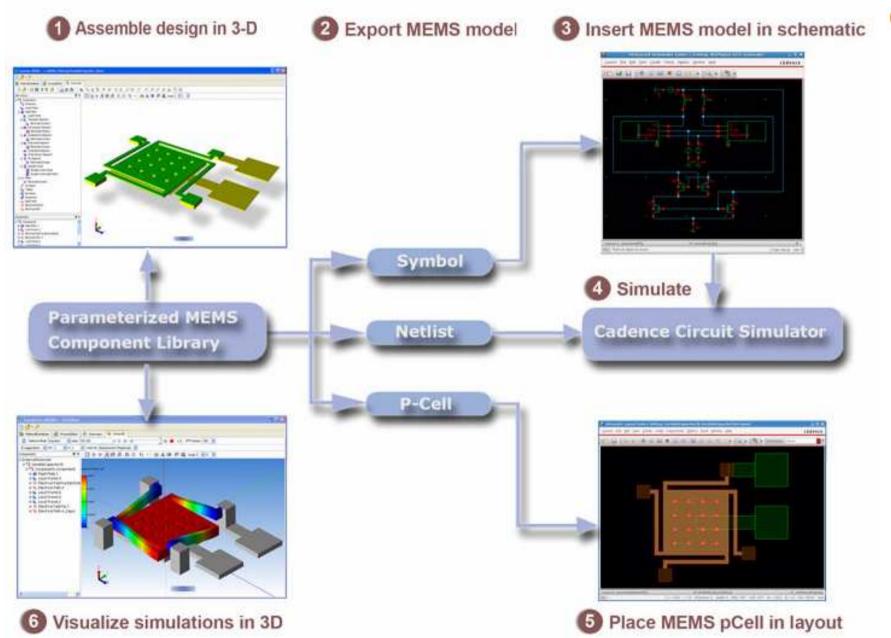


3D-MNT With IC



Design of 3D MEMS with IC

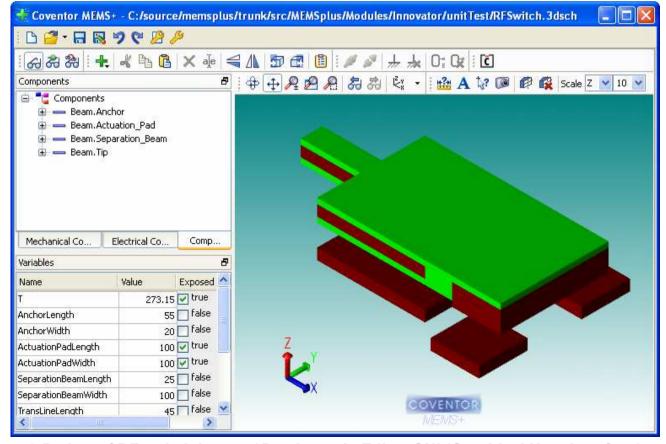




3D Schematic Editor for MEMS

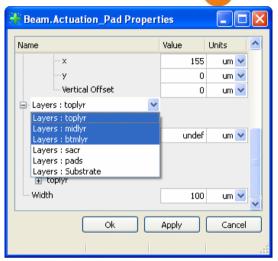
MEMS Design in 3D

- Intuitive 3D environment for device creation
- Based on validated MEMS component library
- Parameterization of material, process and design



3-D view of RF switch in new 3D schematic Editor GUI (Graphical User Interface)





Layer Browser in a Property Window of a Straight Beam Component

			Expression	Units	
□ Aluminum					
■ Visual Prope	erties				
☐ Material Type : Solid		~			
⊆ Solid					
⊕ Wa	fer Orientation	: Euler Angles	~		
- Der	nsity		230	0 kg/m^3	~
⊞ Ela	stic Constants :	Isotropic	~		
⊕ Pre	Stress : In-plan	e Isotropic	~		
⊕ Str	ess Gradient in 2	2 : In-plane Isotropi	~		
⊕ The	ermal Coefficient	of Expansion			
The	Thermal Conductivity		24	0 W/(m*K)	~
Spe	- Specific Heat		93	0 J/(kg*K)	~
Ele	- Electrical Conductivity		.8*T^2-1e6*T+2e	8 S/m	~
Pie	Piezoelectric Coefficients : undef		~		
⊕ Rel	Relative Permittivity : Isotropic		~		
⊕ Pie:					
- Rel	- Relative Permeability				
Coe	Coercivity			A/m	
- Sat	Saturation Magnetization			T	
± Si3N4					
THERM_OXIDE					
■ SILICON					
Variables					8
Name	Value	Exposed			
т		273.15 🔽 true			
		undef false			

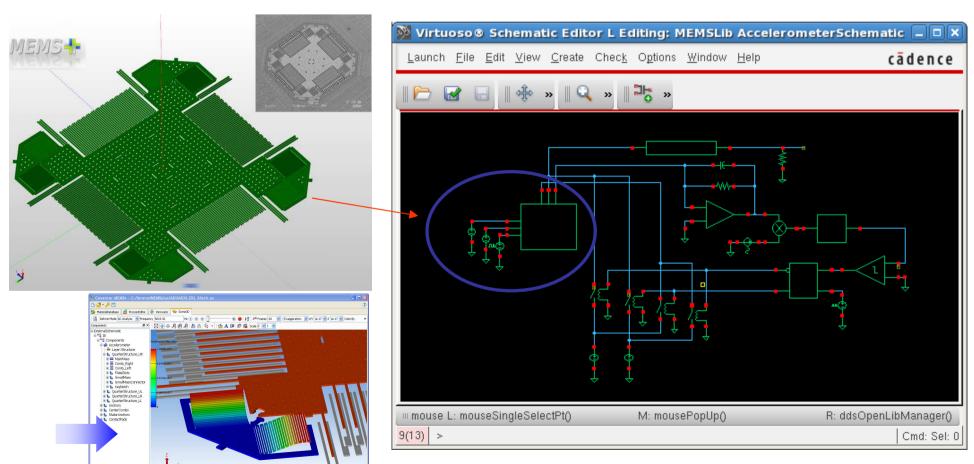
Material Property Editor 5

Integration with MEMS and EDA

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Seamless Connection to IC Design

- The MEMS designer transfers the model to the IC-designer
- The IC designer does electronic system design



HEDORIS

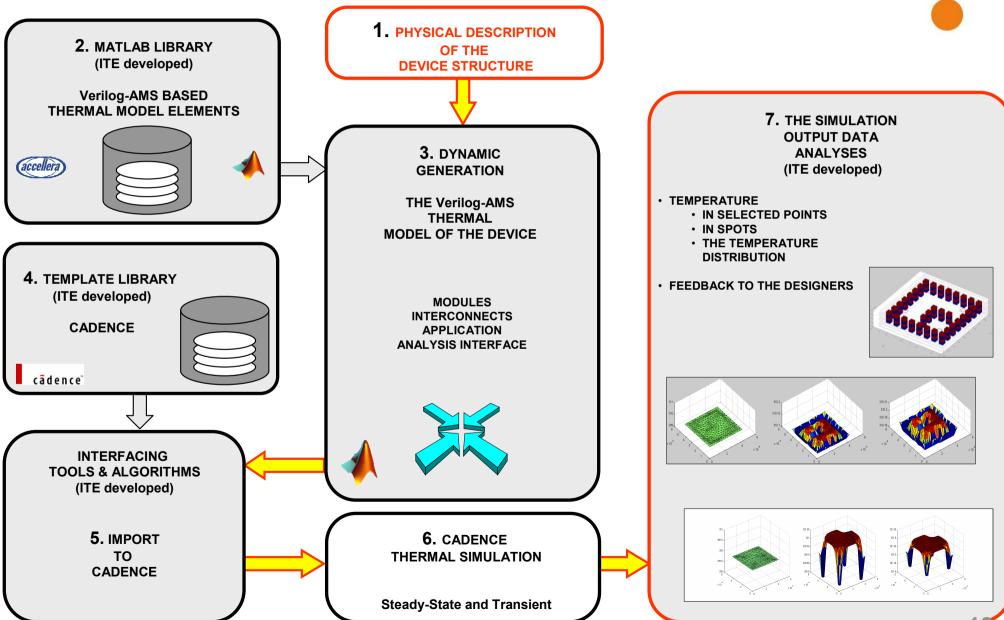


HETEROGENEOUS DEVICE ORIENTED SIMULATION

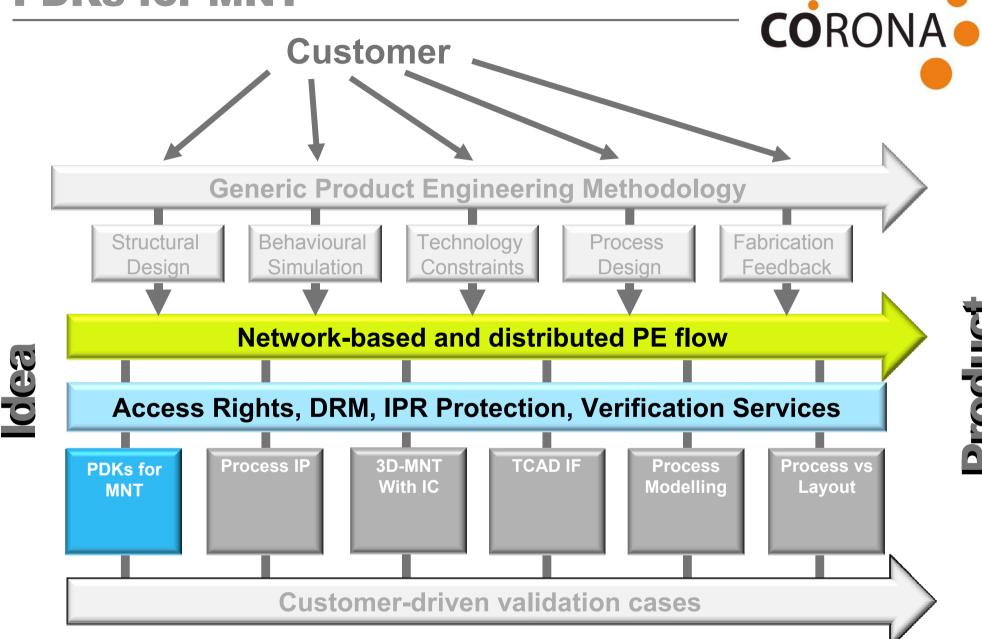
- HDL-based
- 3D multimodule structures
- Fast and easy thermal model implementation
- Thermal device simulation
- Verification of temperature distribution

HEDORIS





PDKs for MNT



Design Kit Motivation





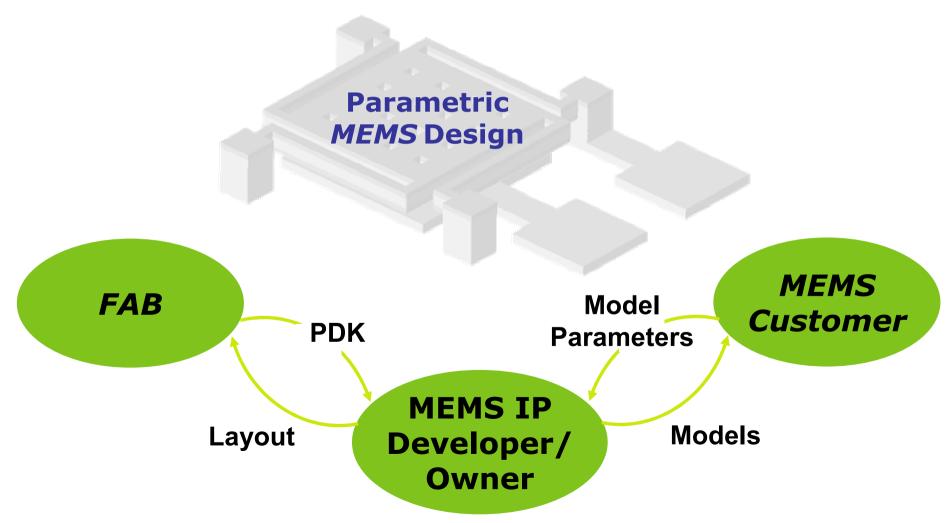


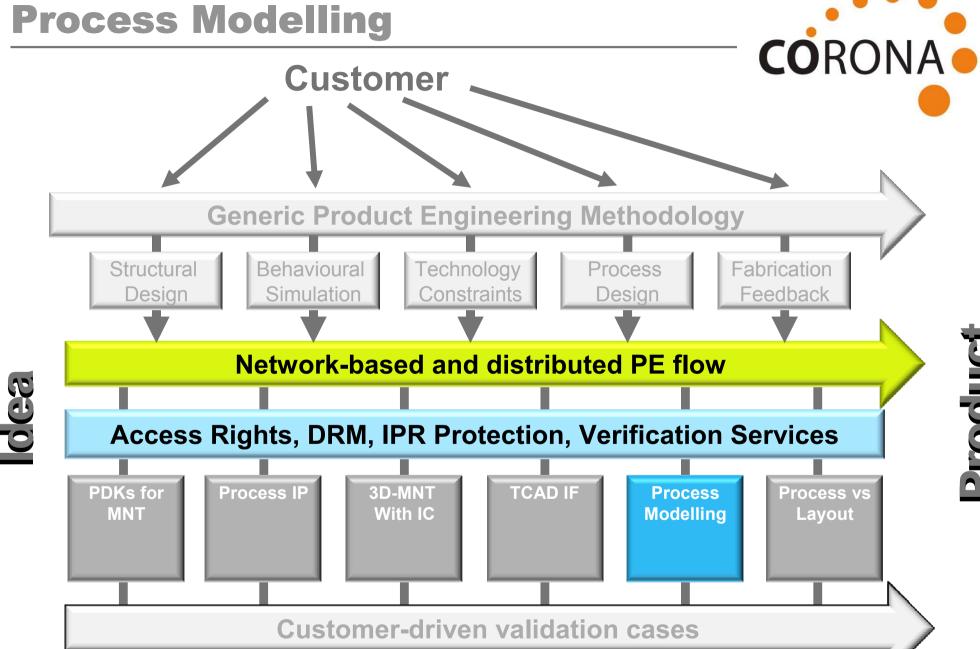
... use tools to build a bridge

Enable MEMS Eco-System



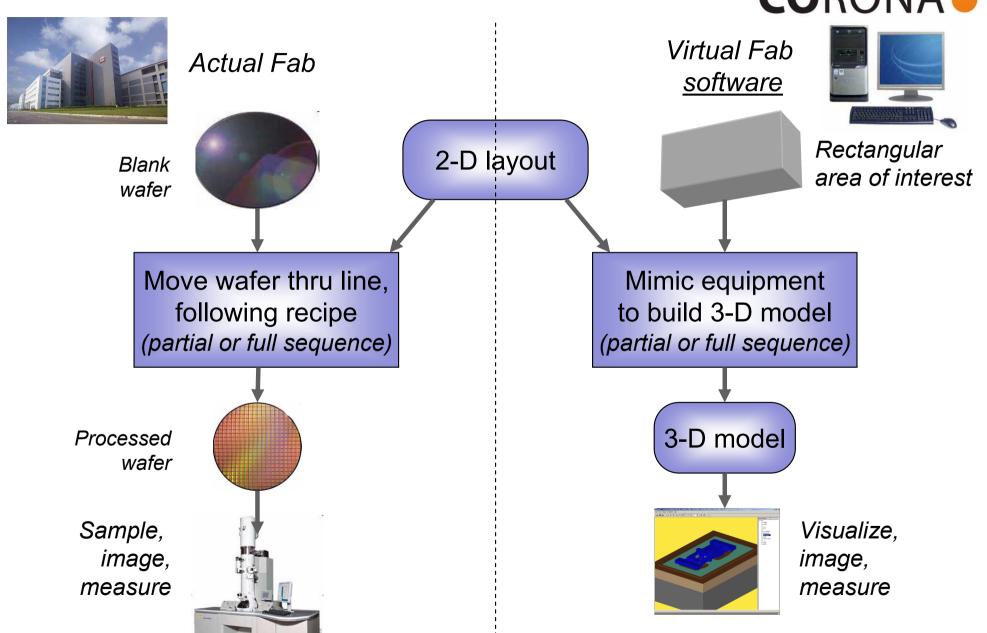
 Facilitate communication between the distributed partners of the MEMS eco-system



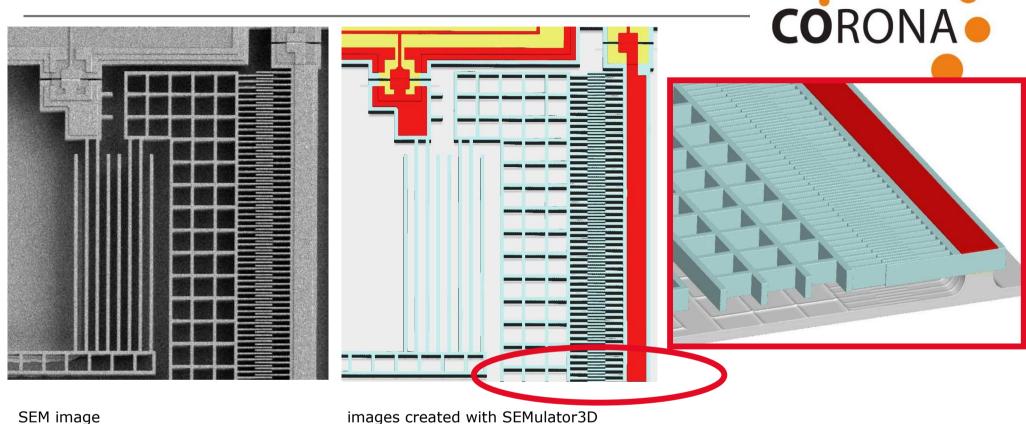


Virtual Fabrication





Use case example: X-FAB SOI

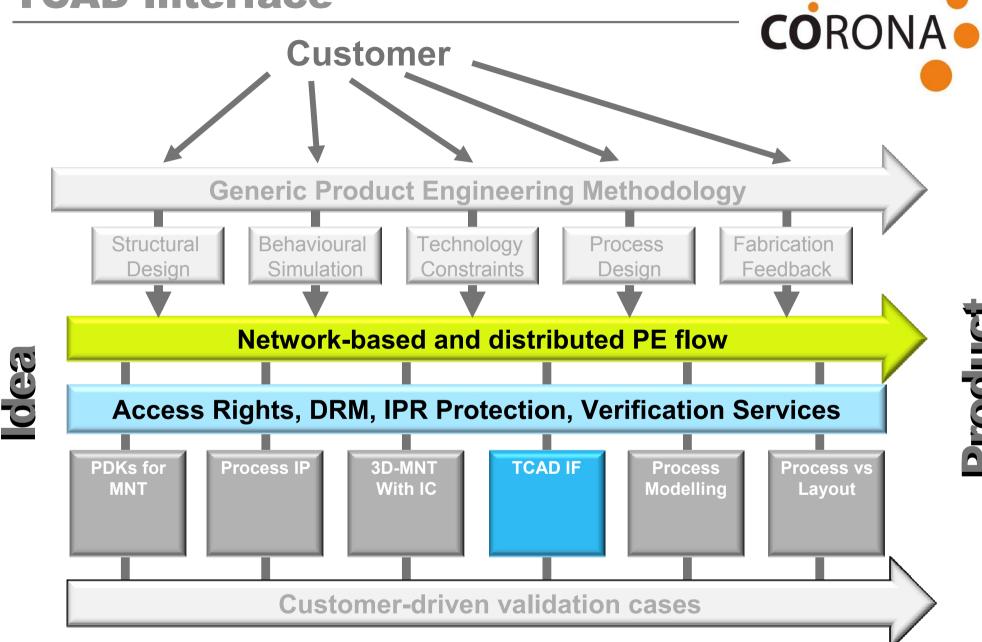


images created with SEMulator3D

X-FAB uses virtual fab runs for...

- Customer support, marketing of MEMS foundry technologies
- Checking new designs prior to actual fabrication
- Process development
- Failure analysis

TCAD Interface

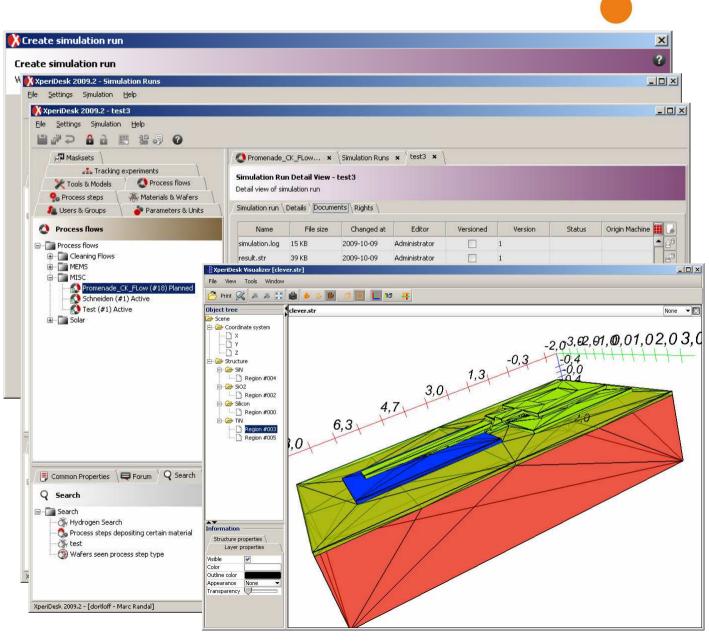




Starting a simulation

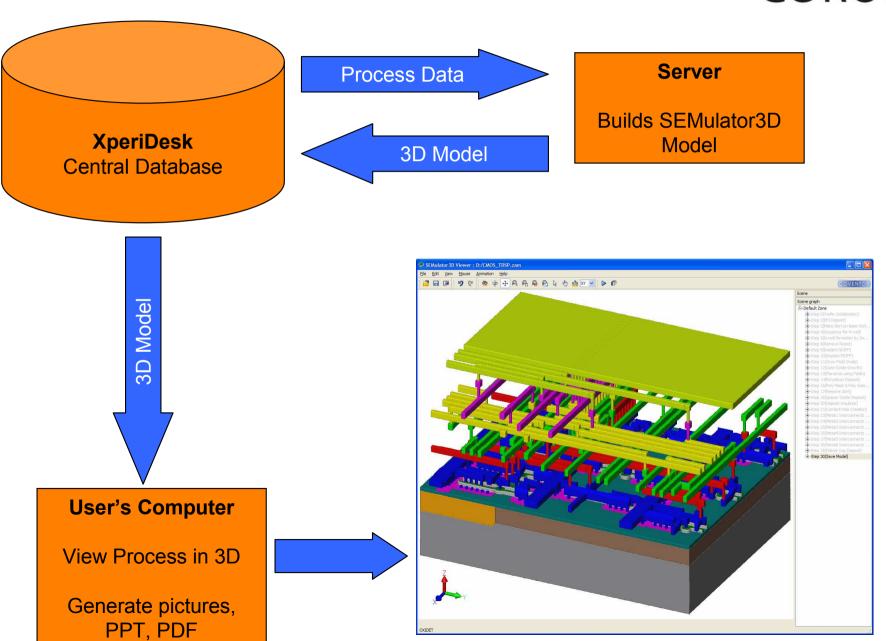
Checking previous runs

Previous run details

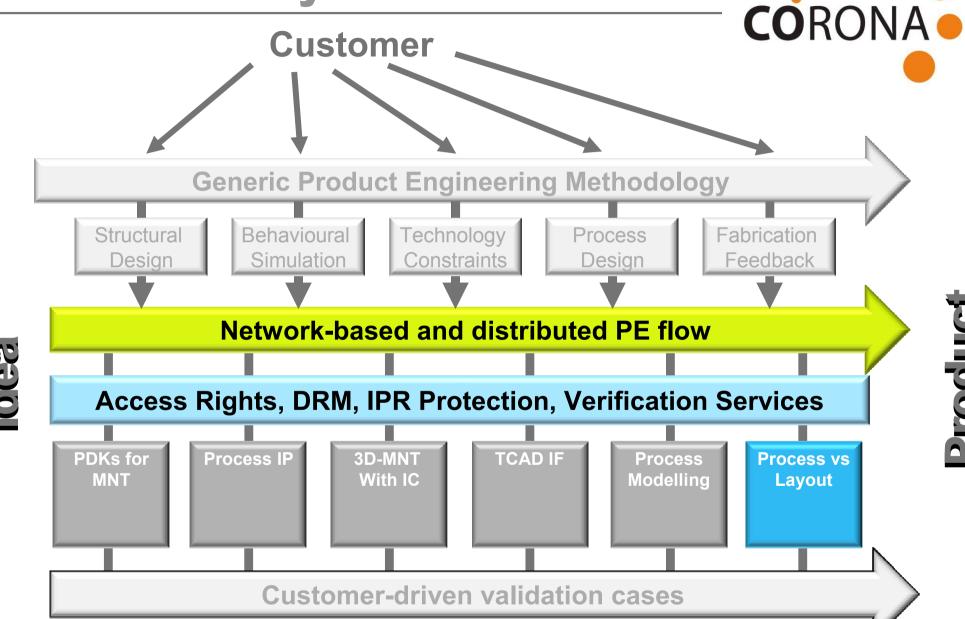


SEMulator3D and XperiDesk Bi-Directional Integration





Process vs. Layout



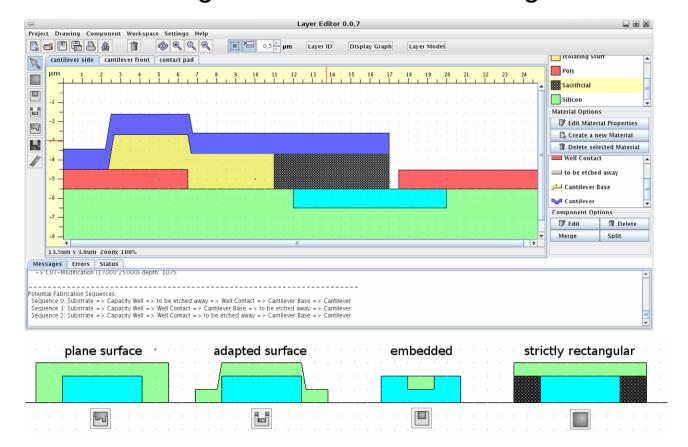
Cross Section Editor Prototype

Cross-Section

Common Method for illustrating process capabilities

Cross-Section Editor

- Drawing support for typical cross-section geometries
- Prevents drawing of non-manufacturable geometries





Physical Layer Analyzer

- Identification and classification of
 - Layers
 - Topological Dependencies
 - Shapes
 - Modifications
- Structural Decomposition
- Preparation of Layer Model

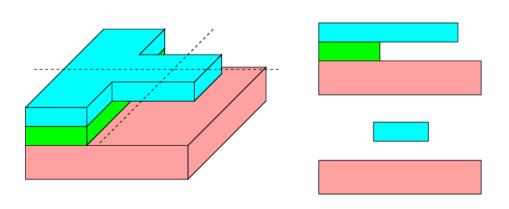
Deposit Green Material

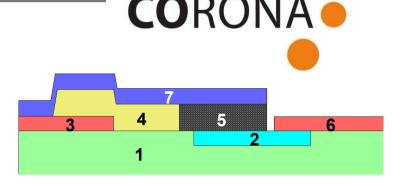
Deposit Blue Material

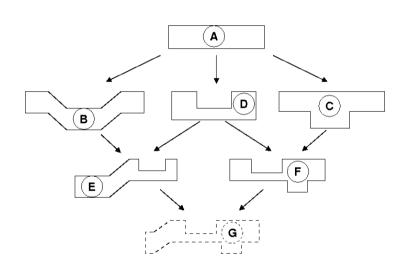
Lithography Cantilever mask

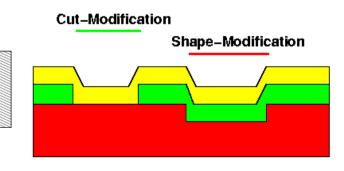
Aniso-Etch Blue Material

Iso–Etch Green Material









Technology Recommender

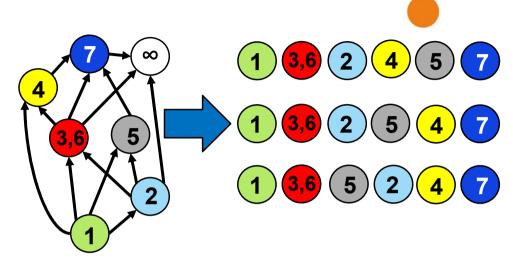
Defines Sequence of

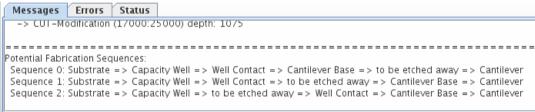
- Layer generation
- Layer modifications
- Lithography masks

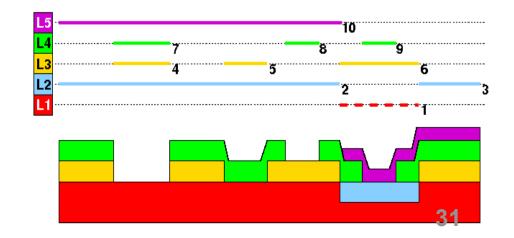
Prepares process draft

- Recipe Search
- Process Design

			Action	
	Layout	Modifications	Visibility	Order
A		-	block	block
В		1	propagate	propagate
С			propagate	block



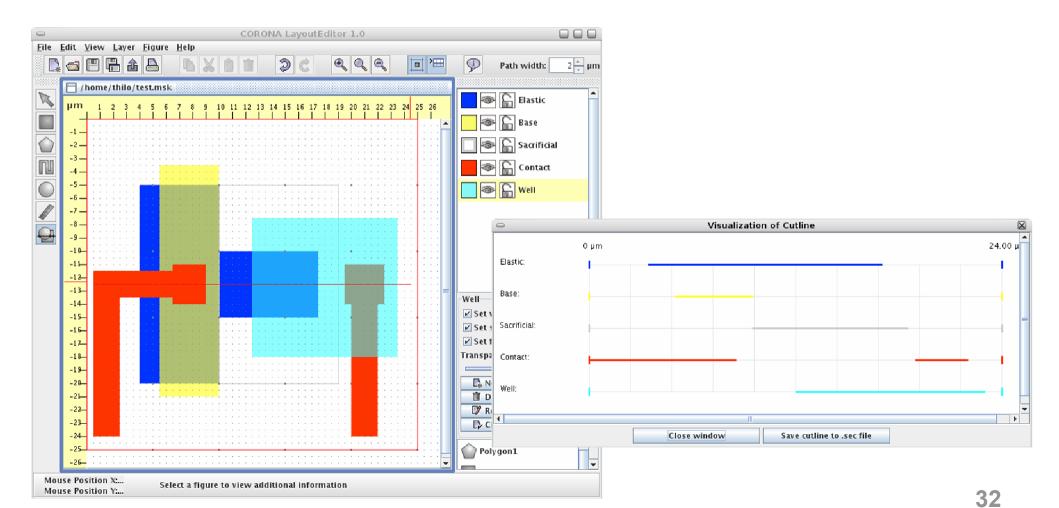




Process vs. Layout

Layout Editor

- CORONA
- Layout editor with basic editing functions
- Goal: Linking layer model (analyzer) to physical layout



Contact



CORONA c/o IVAM Microtechnology Network www.corona-mnt.eu



in hall 6, H16/C1

